

L Number	Hits	Search Text	DB	Time stamp
1	11213	die adj4 pad	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:22
2	4710791	heat (heat sink) (sink spreader slug metal radiate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:25
3	5189	wire and (die adj4 pad) and "4"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:25
4	6463	(semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:27
5	6484	(semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring wirebond)	US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:29
6	2698	((semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring wirebond)) and (bga ball bump flipchip (flip adj chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:29
7	2137	((semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring wirebond)) and (bga ball bump flipchip (flip adj chip))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:30
8	1848	(cap lid cover top) and ((semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring wirebond)) and (bga ball bump flipchip (flip adj chip))) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:31
9	1390	((cap lid cover top) and (((semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring wirebond)) and (bga ball bump flipchip (flip adj chip))) and substrate)) and (epoxy encapsulant encapsulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:32
10	355	((cap lid cover top) and (((semiconductor chip dice ic (integrated adj circuit) die) and (die adj4 pad) and (wire wiring wirebond)) and (bga ball bump flipchip (flip adj chip))) and substrate)) and (epoxy encapsulant encapsulation)) and (retainer ring guard)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/22 11:32